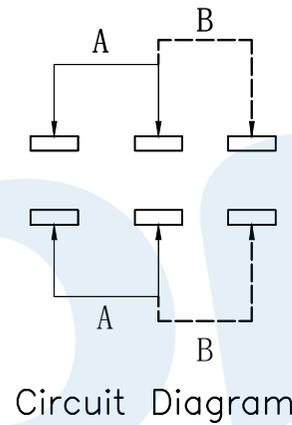
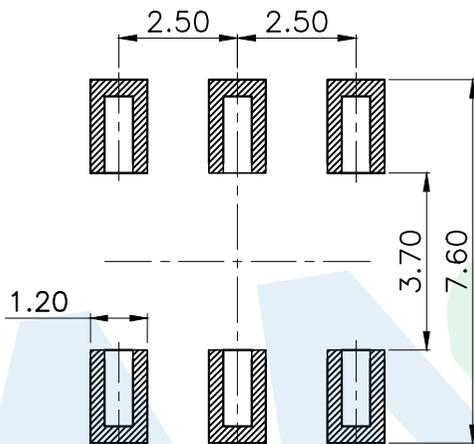
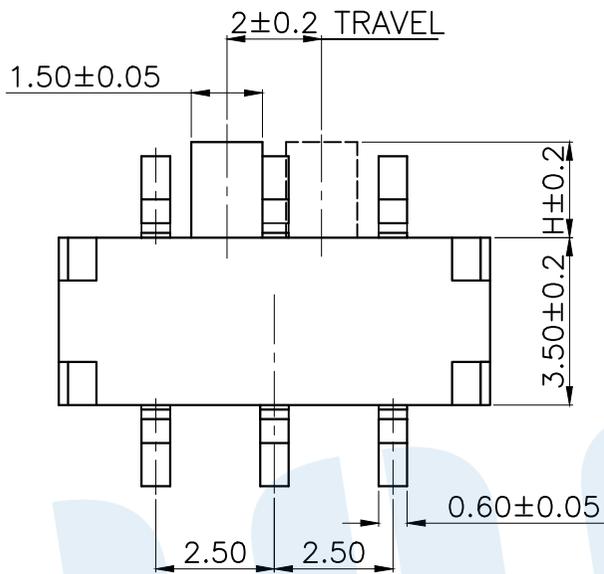
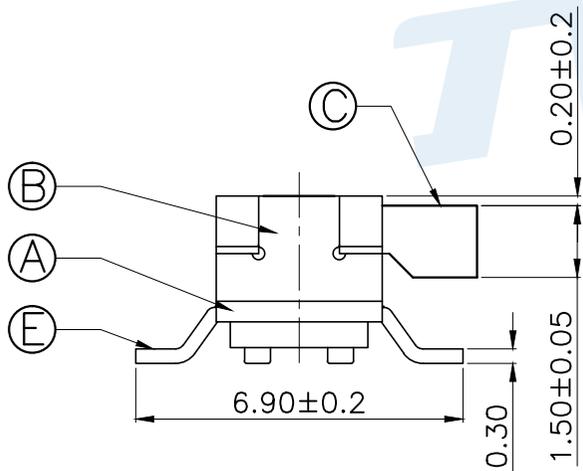
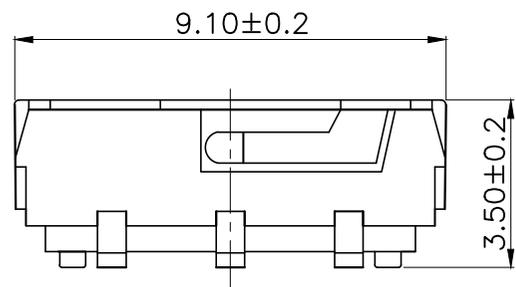


RoHS



PCB Layout(Pattern side)

Circuit Diagram



Code	H	Operating force
A1	2.0	200±80gf
A2	3.0	
A3	4.0	

NO.	Name	Number	Qty	Materil	Remarks
⑤	Terminal		6	Brass	Silver
④	Contact reed		2	Beryllium copper	Silver covered
③	Handle		1	PA46	Black
②	Cover		1	SUS	Silver
①	Base		1	PA46	Black

**YUANDI®** Yuandi Electronics Co, Ltd

design	date	name	TOGGLE SWITCH
Review	date	model	TA-3531S-A□
Approved	date		

Drawing number: Proportion 1:1 unit mm gage number A4

modify Review Approved Tolerance not specified

angle	±2'
10~30	±0.30
5~10	±0.20
~ 5	±0.10



# 东莞市元迪电子有限公司

## Dongguan YuDing Electronic Co.,Ltd

额定值 RATING

一、电气性能规 ELECTRICAL CHARACTERISTICS

项目 ITEM	测试条件 TEST CONDITIONS	表现 PERFORMANCE
接触电阻 Contact Resistance	在微小电流(100mA)以下测试 Measured at small current (100mA or less) 1000HZ	80 毫欧以下 80mΩ Max
绝缘电阻 Insulation Resistance	输入 500V DC 电压 1 分钟,按以下接触方法测试: Apply a voltage of 500V DC for 1 min to following portions after which measurement shall be made: (1)Between body and conductor (1)塑胶体与针脚之间 (2)Between conductor not to be contact (2)不接触的针脚之间	100 兆欧以上 100MΩ Min
耐电压 Dielectric Strength	输入 AC 500V (50-60HZ)电压, 1 分钟感应电流为 0. 5mA, 按以下接触方法测试: AC 500V ims (50-60HZ) for 1 min trip current: 0. 5 mA (1)Between terminals (1)塑胶体与排脚之间 (2)Between individual terminals and frame (2)不接触的排脚之间	没有绝缘破坏等异常 NO damage to parts arcing, or breakdown etc
使用温度范围 Practical Temperature Range	在-20° C — +75° C 温度内使用 -20° C — +75° C	
测试标准状态 Standard Atmospheric Conditions	在没有指定的情况下测试温度,湿度, 气压如下: Unless otherwise specified, the standard range or atmospheric conditions for making measurements and tests are as follows (1)Ambient temperature:5° C to 35° C (1)温度为 5X -- 35C (2)Relative humidity:45% to 85% (2)湿度为 45% — 85% (3)Air pressure :80Kpa to 106Kpa (3)气压为 80Kpa — 106Kpa	

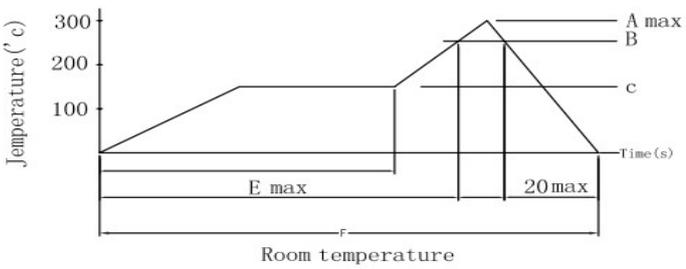
二、机械性能规格 MECHANICAL CHARACTERISTICS

动作力 Operation Force		200gf±80gf
端子强度 Terminal Strength	在排脚前端任意一个方向的先端加上 300gf 力度测试,时间为 15 秒 A static load of 300gf shall be applied to the tip of the terminal for 15 sec in any directio	在排脚中没有裂开, 松动 等异常,满足于机械, 电器性能 .Electrical characteristics shall be satisfied without damage or excessive looseness of terminals
寿命测试 Life Test	无负荷: 在无负荷的条件下以分钟 25-30 回的速度进行 10,000 次的测试 1:Endurance without loading: A switch shall be subjected to 10,000 cycles at a speed of 25-30 cycles for 1 min 负荷: 在负荷的条件下以每分钟 25-30 次的频率做 5,000 回之负荷测试 2. Endurance with loading: A switch shall be subjected to 5,000 cycles at a speed of 25-30 cycles for 1 min	接触电阻不能超过 100 毫欧 1. Contact resistance shall be 100m Q Max 其他满足于机械, 电器 性能(2) Mechanical and electriccal Characteristics shall be satisfied

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三、耐久性 DURABILITY		
可焊性试验 Solderability Test	温度为 230±5° C, 时间为 3±0.5 秒 The solder bath of 230±5°C for 3±0.5 seconds	焊锡部分粘锡均匀,饱满, 锡面平滑 Area of soldering need be smooth and good performance

三、耐久性 DURABILIT		
项目 ITEM	测试条件 TEST CONDITIONS	表现 PERFORMANCE
耐热试验 Heat	放置在温度 85±2° C 中测试 96 小时后, 再放置正常室温中 1 小时来测定。 The switch shall be stored at a temperature of 85±2°C for 96 hours, then the switch shall be maintained at standard atmospheric condition for 1 hour after which, measurement shall be made	外观无异常, 能满足于机械, 电器性能 There shall be no deformation or cracks in molded part
耐冷实验 Cold Test	放置在温度 -20±3° C 中 96 小时后, 再放置常温中 1 小时来进行测试 The switch shall be stored at a temperature of -20 ± 30C for 96 hours, Then the switch shall be maintained at standard atmospheric condition for 1 hour after which measurement shall be made	
潮湿实验 Humidity	放置在 40±2° C 实验的相对湿度为 90%-96%环境中 96 小时后, 再将样板放在正常环境 1 小时后进行测试。 The switch shall be stored at a temperature of 40+2°C and a humidity of 90%-96% for 96 hours, then the switch shall be maintained at standard atmosphere condition for 1 hour after which measurement shall be made	

耐焊性试验 Resistance To Soldering Heat Test	<p>焊炉焊接的时候温度控制在 255±5° C,过炉时间 3±0.5 秒, 于(基板)厚度应 1.6mm Solder bath method: Solder temperature 255 +5°C , immersion time 3+0.5 sec, immersion depth up to the surface of the board thickness of printed wiring board 1.6mm dimensions of component holes in the printed wiring board shall be accordance to the specification</p> <p>(1) 加热方式: 上下平均加热, 标准波峰炉.Heating method:Double heating method with infrared heater.</p> <p>(2) 温度测定方式: 用减温探棒迅速接于铜箔表面上检测.Temperature measurement: Thermocouple 0.1 to 0.2 0 ca (k) or cc (t) at soldering portion (copper foil surface) a heat resisting tape should be used for fixed measurement</p> <p>(3)温度示意图.Temperature profile.</p> <p>(4) 测试报告是以 PC 板铜箔面作基准, 因 PC 板与开关之温差是直接受 PC 板之物料, 大小, 厚度等影响, 不论任何情况及条件都需要避免防止开关表面温度超过 255° C The condition mentioned abover is the temperature on the mounting surface of a pc board, there are cases where the pc 1)00^ s temperature greatly differs from that of the switch, depending on the pc board*s material, size, thickness, etc. care should be taken to prevent the switch*s surface temperature from exceeding 255°C</p> <p>(5) 条件变化是直接受回流焊接仪器影响, 请注意, 其仪器是否正常 Soldering conditions differ depending on reflow soldering machine, you are requested to verify the soldering conditions thoroughly beforehand.</p>	本体无变形, 能满足机械, 电器性能 Without deformation of case or excessive looseness of teminals electriccal. Characteristics shall be satisfied.
		

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